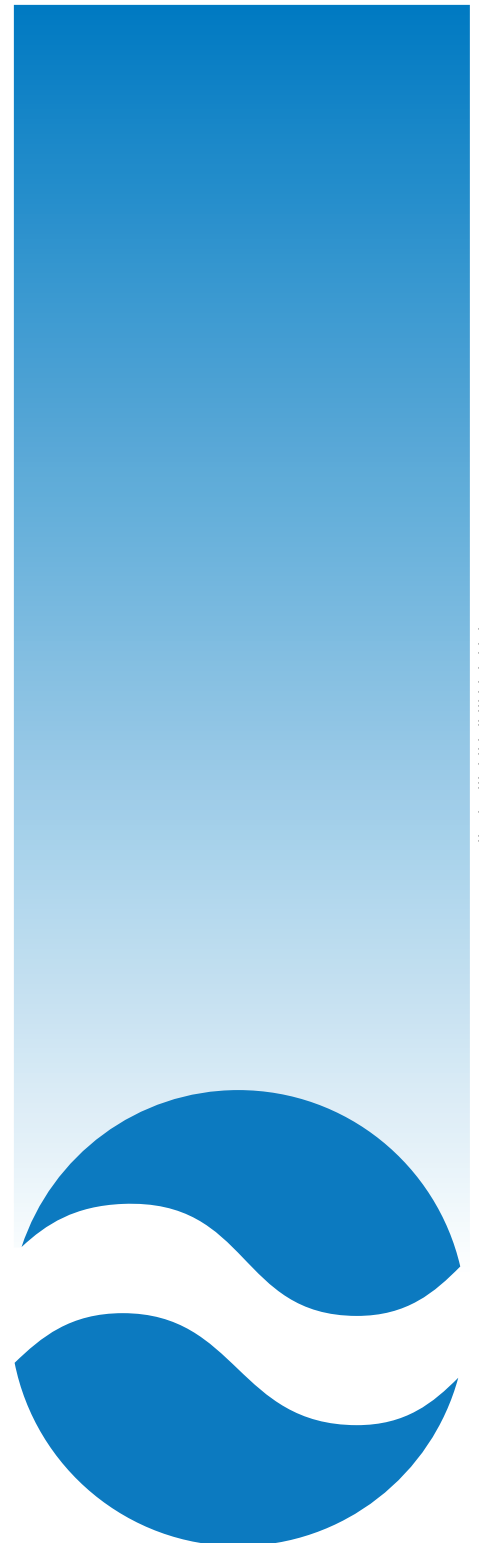


IPC/JEDEC J-STD-033D
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August 2014

***JOINT
INDUSTRY
STANDARD***

Handling, Packing,
Shipping and
Use of Moisture,
Reflow, and Process
Sensitive Devices



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The material in this joint standard was developed by the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the IPC Plastic Chip Carrier Cracking Task Group (B-10a)

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IPC/JEDEC J-STD-033D



Handling, Packing, Shipping and Use of Moisture, Reflow, and Process Sensitive Devices

A joint standard developed by the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the B-10a Plastic Chip Carrier Cracking Task Group of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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